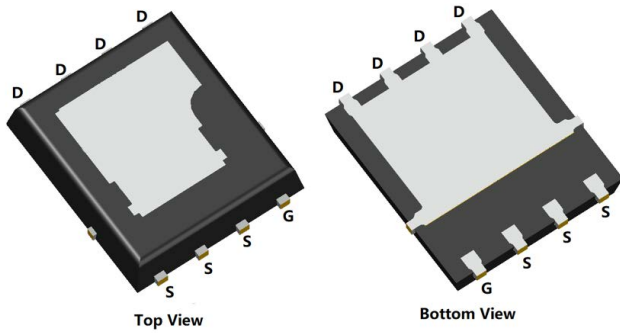
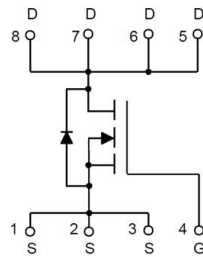


N-Channel Enhancement Mode Field Effect Transistor



PDFN5060-8L



Product Summary

- V_{DS} 40V
- I_D 375A
- $R_{DS(ON)}$ (at $V_{GS}=10V$) $<0.85m\Omega$
- 100% EAS Tested
- 100% ∇V_{DS} Tested

General Description

- Split gate trench MOSFET technology
- Excellent package for heat dissipation
- High density cell design for low $R_{DS(ON)}$
- Moisture Sensitivity Level 1
- Halogen Free
- Epoxy Meets UL 94 V-0 Flammability Rating

Applications

- Power switching application
- Uninterruptible power supply
- DC-DC convertor

Limiting Values

Parameter	Conditions		Symbol	Min	Max	Unit
Drain-source Voltage			V _{DS}	-	40	V
Gate-source Voltage			V _{GS}	-20	20	
Continuous Drain Current (Note 1,2)	Steady-State	T _A =25°C,V _{GS} =10V	I _D	-	45	A
		T _A =100°C,V _{GS} =10V		-	31	
Continuous Drain Current (Note 1,3)	Steady-State	T _C =25°C,V _{GS} =10V,Chip limitation		-	375	
		T _C =100°C,V _{GS} =10V		-	265	
Pulsed Drain Current	T _C =25 °C,t _p ≤10μs		I _{DM}	-	1500	
Maximum Body-Diode Continuous Current	T _C =25 °C		I _S		185	
Avalanche energy (non-repetitive)	T _J =25°C,V _G =10V, R _G =25Ω, L=0.5mH, I _{AS} =39.6A		EAS	-	392	mJ
Total Power Dissipation (Note 1,2)	Steady-State	T _A =25°C	P _D	-	3	W
		T _A =100°C		-	1.5	
Total Power Dissipation (Note 1,3)	Steady-State	T _C =25°C		-	205	
		T _C =100°C		-	102	
Junction and Storage Temperature Range			T _J , T _{STG}	-55	175	°C

Thermal Resistance

Parameter		Symbol	Typ	Max	Units
Thermal Resistance Junction-to-Ambient (Note 2)	Steady-State	$R_{\theta JA}$	-	50	$^{\circ}C/W$
Thermal Resistance Junction-to-Case	Steady-State	$R_{\theta JC}$	-	0.73	
Thermal Resistance Junction-to-top-plate	Steady-State	$R_{\theta Jtp}$	-	0.93	

Ordering Information (Example)

PREFERED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
SCGCD85G04HR	F1	GCD85G04HR	5000	10000	100000	13" reel

■ Electrical Characteristics

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =1mA, T _j =25℃	40	-	-	V
		V _{GS} =0V, I _D =10mA, T _j =25℃	40	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =32V, V _{GS} =0V, T _j =25℃	-	-	1	μA
		V _{DS} =32V, V _{GS} =0V, T _j =100℃	-	-	100	
Gate-Source Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V, T _j =25℃	-	-	±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA, T _j =25℃	2	2.8	4	V
Static Drain-Source On-Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =20A, T _j =25℃	-	0.63	0.85	mΩ
Diode Forward Voltage	V _{SD}	I _S =20A, V _{GS} =0V, T _j =25℃	-	0.74	1.2	V
Gate Resistance	R _G	f=1MHz, T _j =25℃	-	2	-	Ω
Dynamic Parameters						
Input Capacitance	C _{iss}	V _{DS} =20V, V _{GS} =0V, f=1MHz, T _j =25℃	-	5410	-	pF
Output Capacitance	C _{oss}		-	3390	-	
Reverse Transfer Capacitance	C _{rss}		-	230	-	
Switching Parameters						
Total Gate Charge	Q _g	V _{GS} =10V, V _{DS} =20V, I _D =50A, T _j =25℃	-	79	-	nC
Gate-Source Charge	Q _{gs}		-	24	-	
Gate-Drain Charge	Q _{gd}		-	17	-	
Reverse Recovery Charge	Q _{rr}	I _F =50A, di/dt=100A/μs, V _{GS} =0V, V _R =20V, T _j =25℃	-	87	-	nC
Reverse Recovery Time	t _{rr}		-	78	-	ns
Turn-on Delay Time	t _{D(on)}	V _{GS} =10V, V _{DS} =20V, I _D =50A, R _{GEN} =6Ω, T _j =25℃	-	26	-	ns
Turn-on Rise Time	t _r		-	36	-	
Turn-off Delay Time	t _{D(off)}		-	60	-	
Turn-off Fall Time	t _f		-	47	-	

Note:

- The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
- The value of $R_{\theta JA}$ is measured with the device mounted on the 40mm*40mm*1.1mm single layer FR-4 PCB board with 1 in² pad of 2oz. Copper, in the still air environment with $T_A=25^{\circ}C$. The maximum allowed junction temperature of $175^{\circ}C$. The value in any given application depends on the user's specific board design.
- Thermal resistance from junction to soldering point (on the exposed drain pad).

■ Typical Electrical and Thermal Characteristics Diagrams

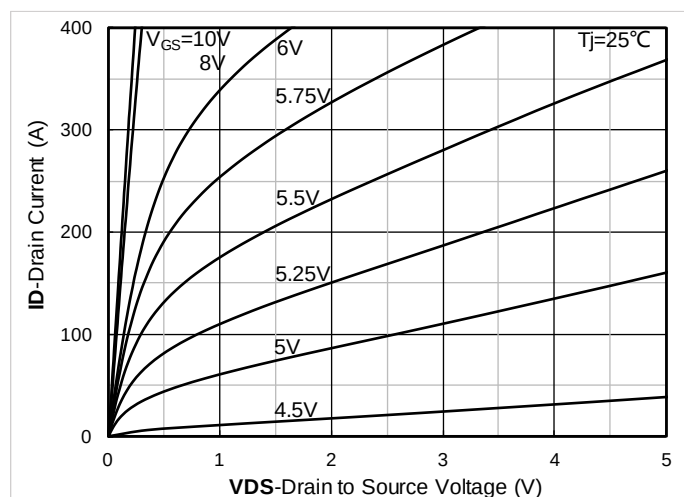


Figure 1. Output Characteristics; typical values

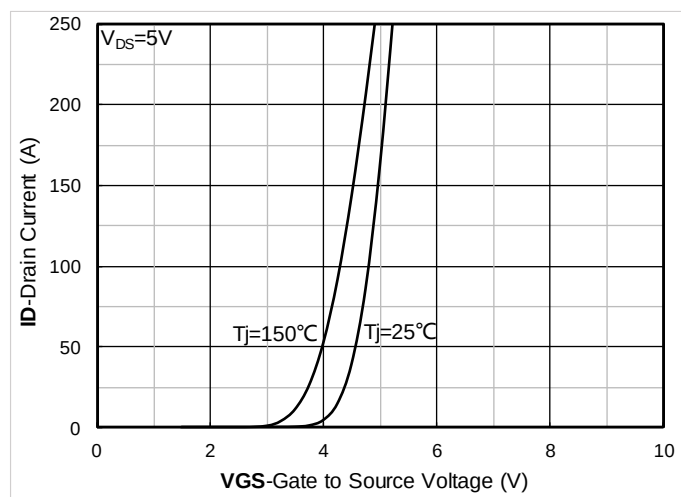


Figure 2. Transfer Characteristics; typical values

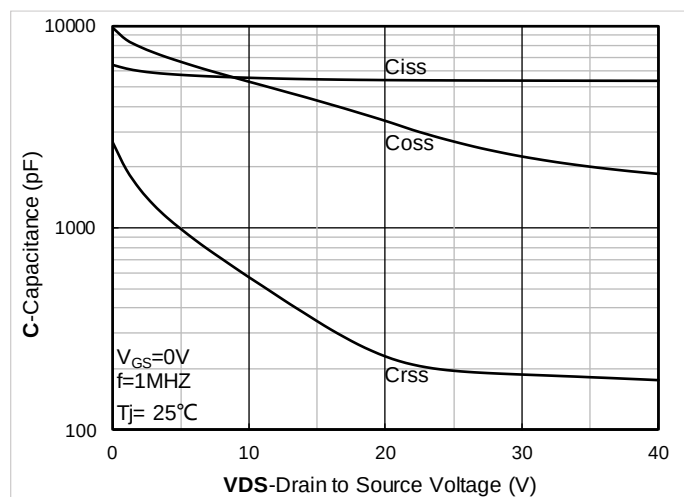


Figure 3. Capacitance Characteristics; typical values

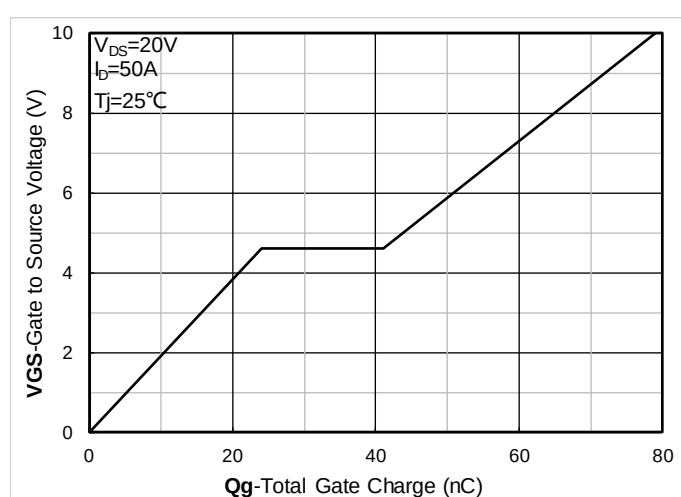


Figure 4. Gate Charge; typical values

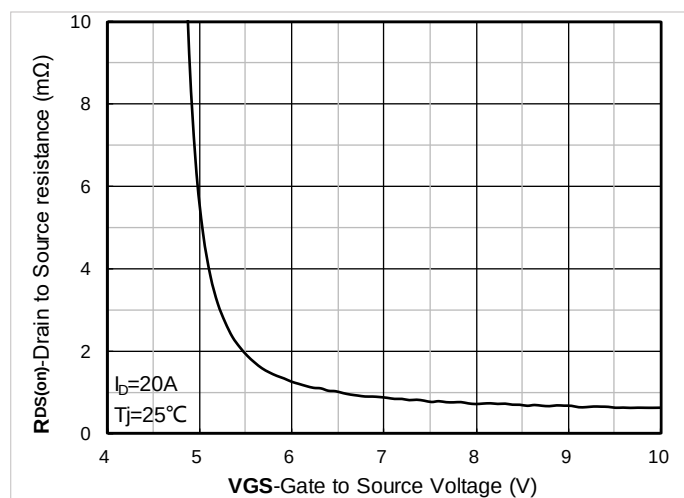


Figure 5. On-Resistance vs. Gate to Source Voltage; typical values

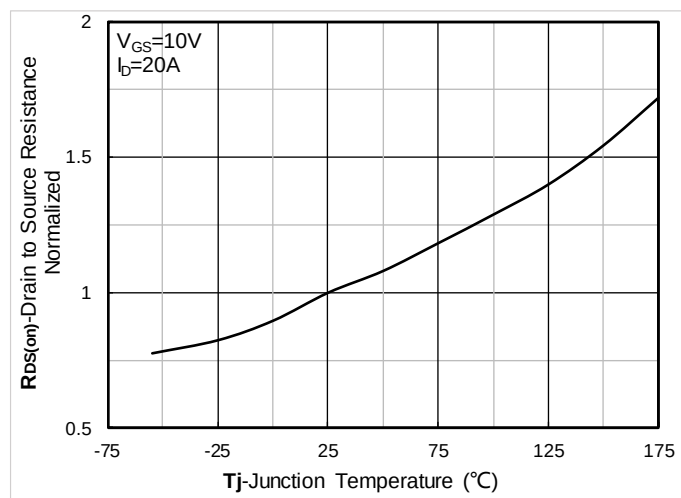


Figure 6. Normalized On-Resistance

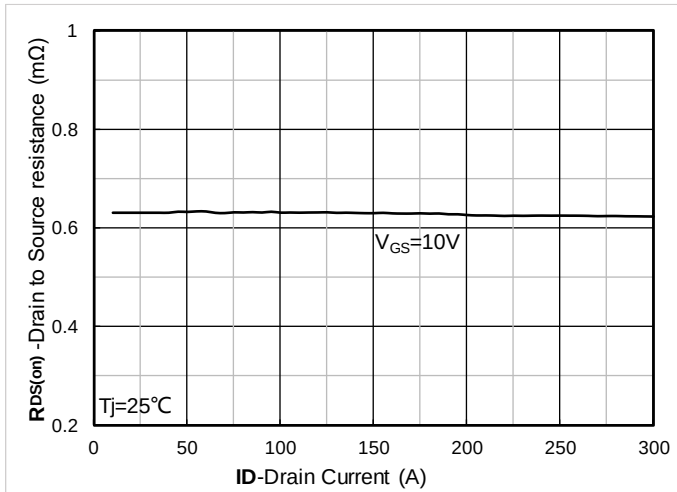


Figure 7. $R_{DS(on)}$ vs. Drain Current; typical values

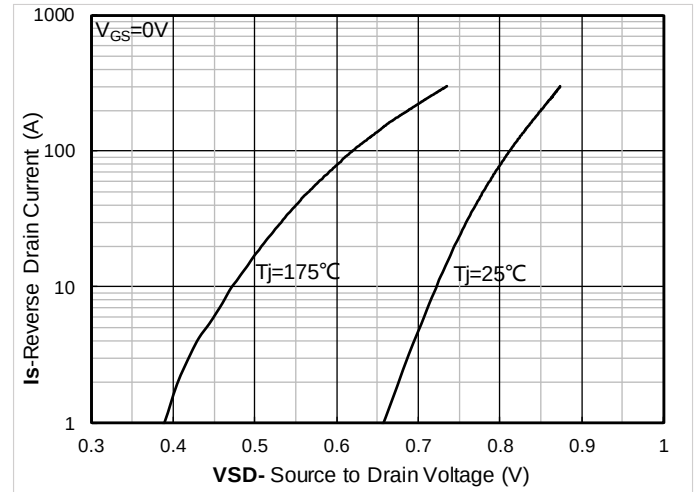


Figure 8. Forward characteristics of reverse diode; typical values

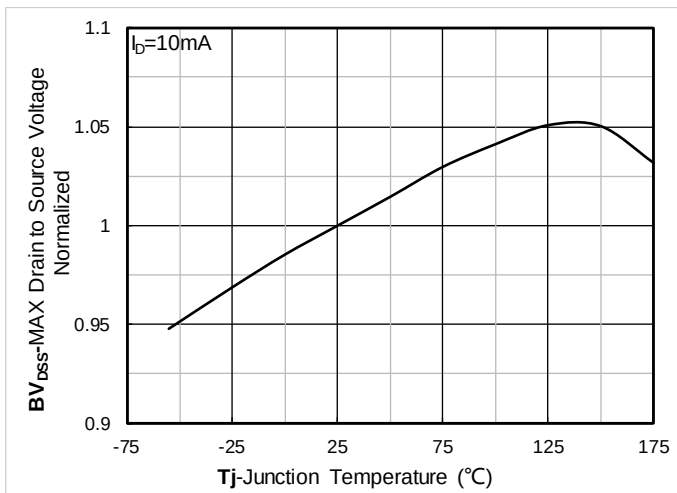


Figure 9. Normalized breakdown voltage

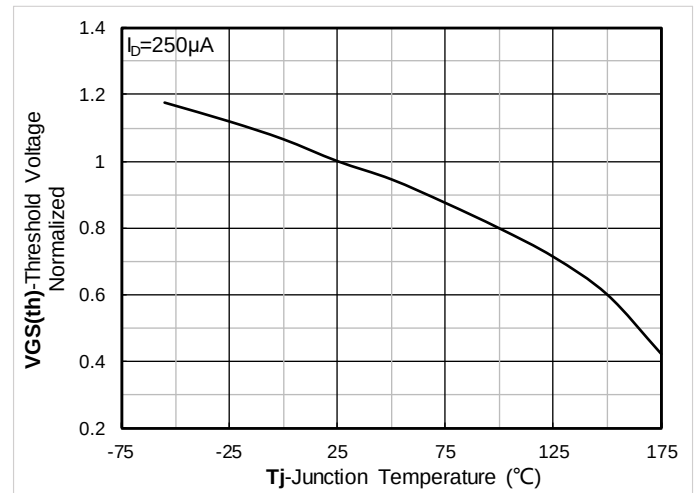


Figure 10. Normalized Threshold voltage

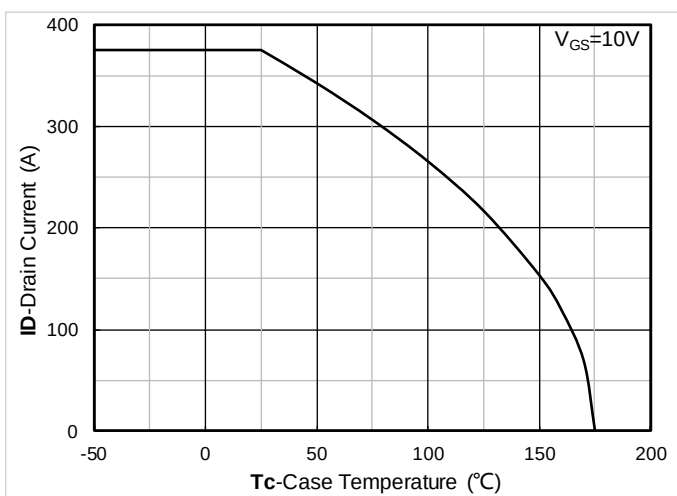


Figure 11. Current dissipation

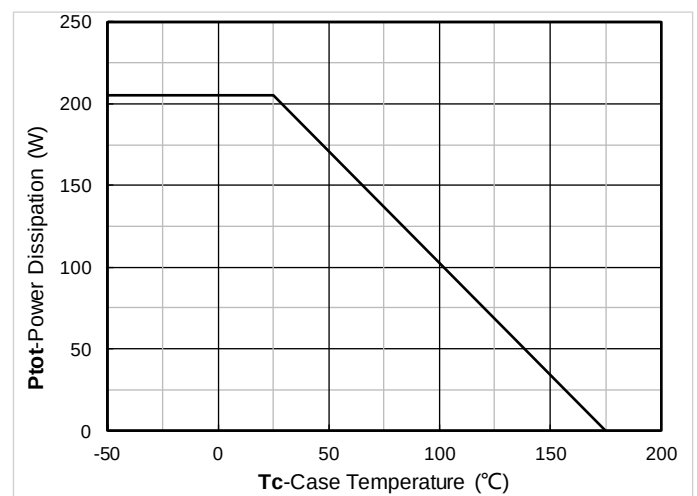


Figure 12. Power dissipation

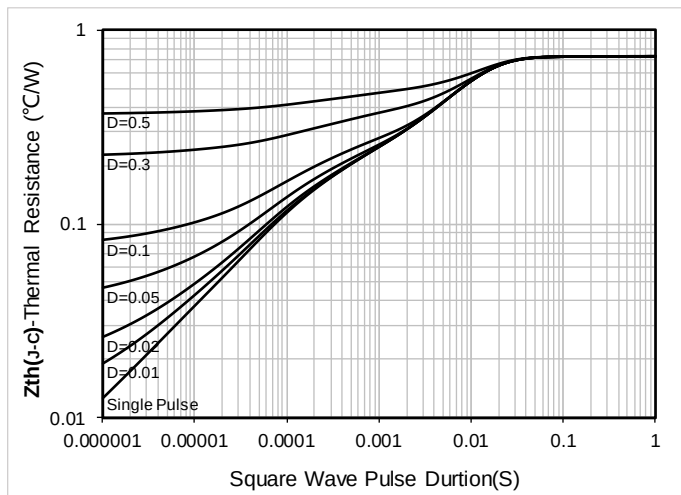


Figure 13. Maximum Transient Thermal Impedance

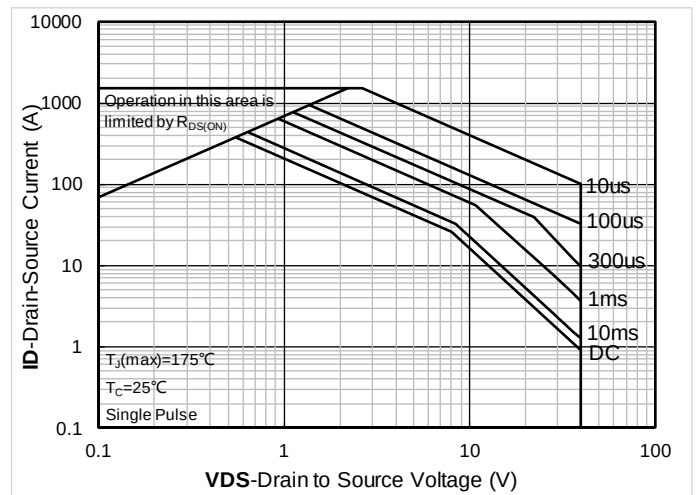
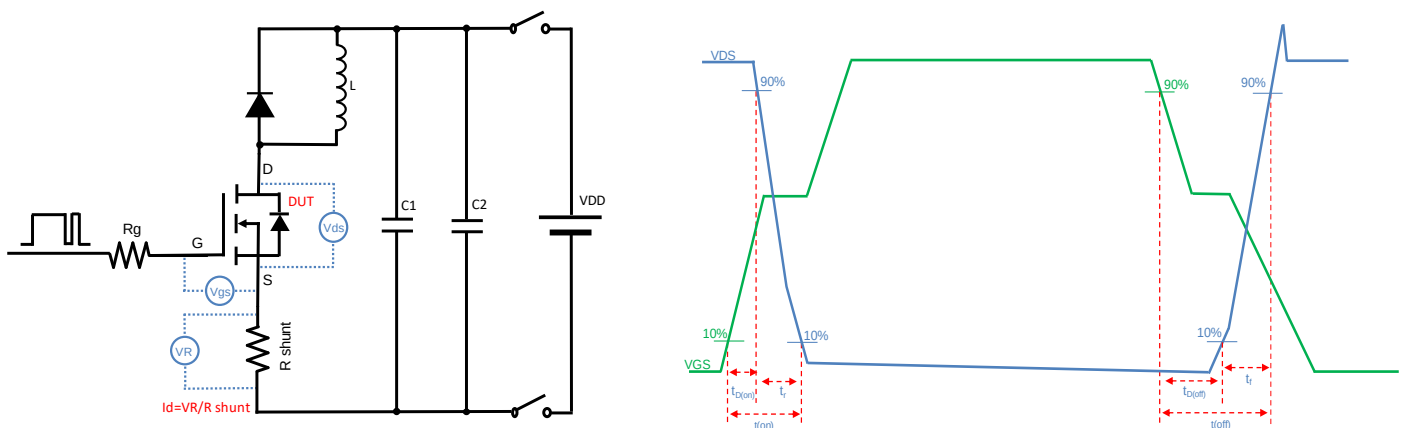
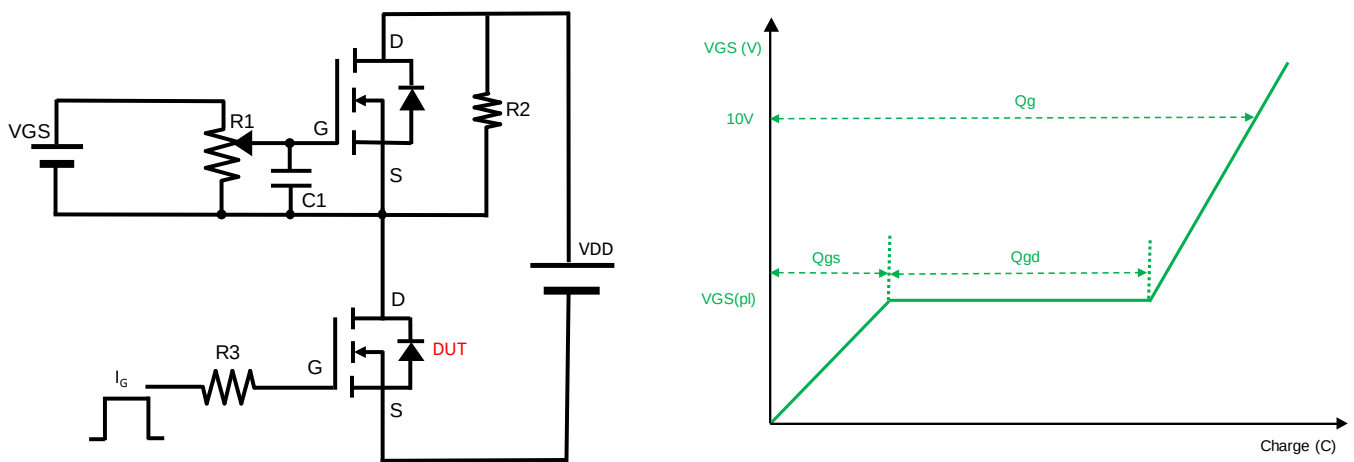
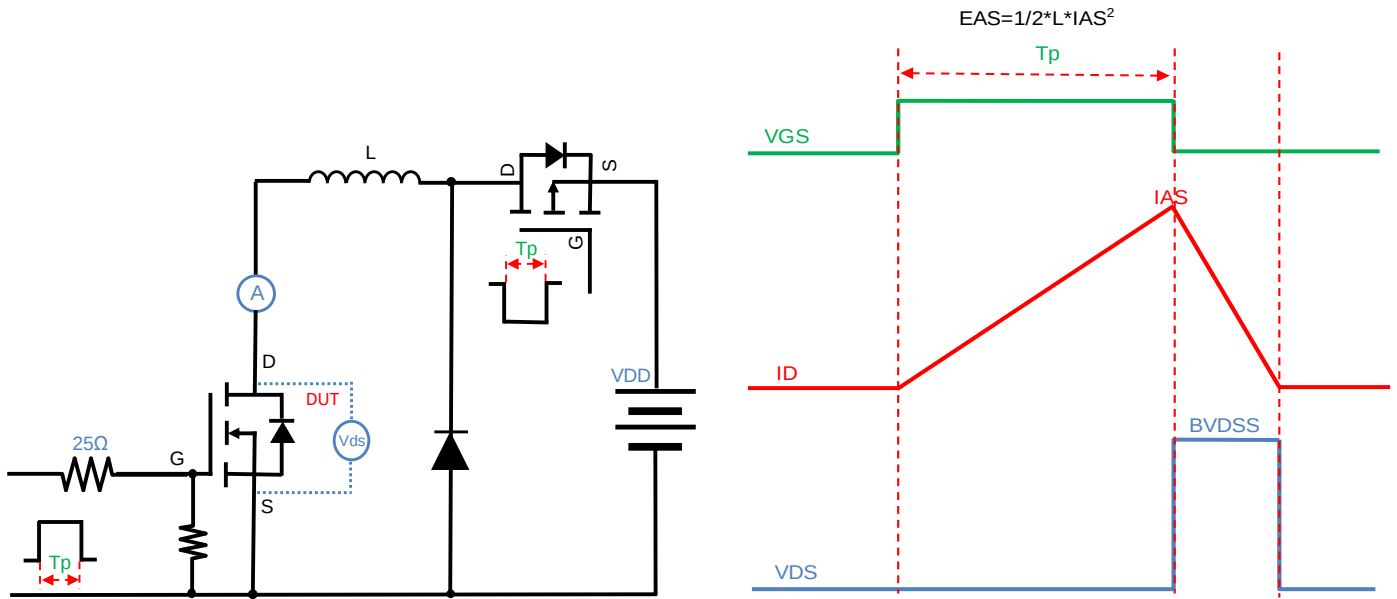


Figure 14. Safe Operation Area

■ Test Circuits & Waveforms



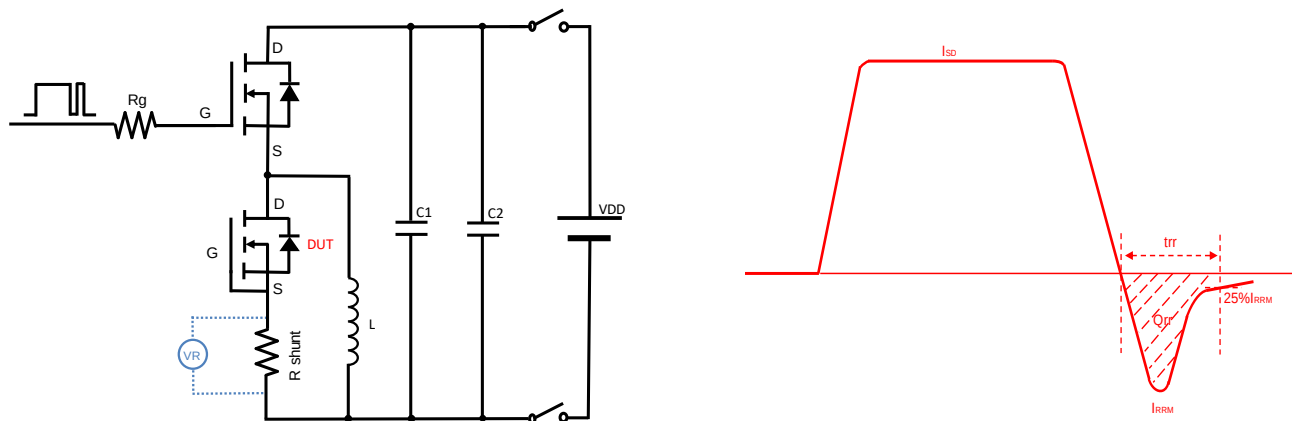
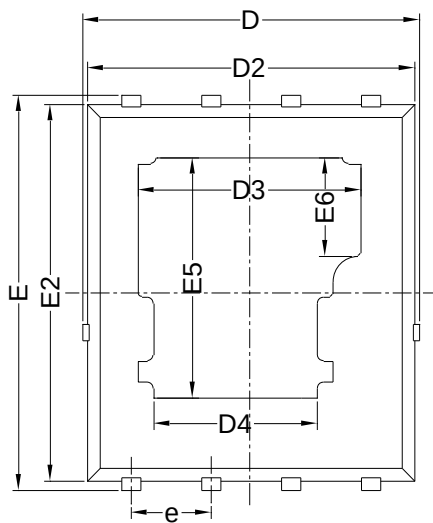
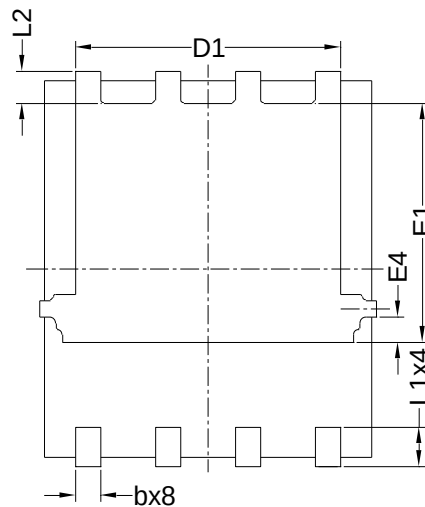


Figure D. Diode Recovery Test Circuit & Waveform

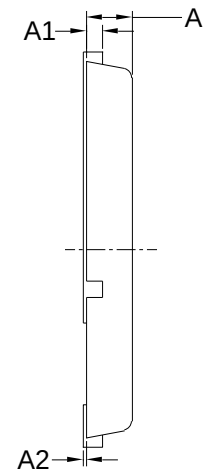
■ PDFN5060-8L-DSC Package information



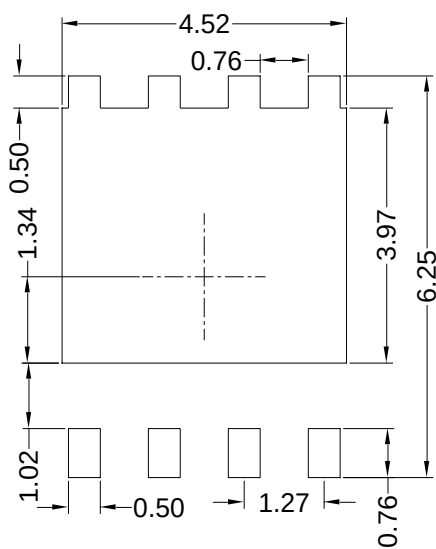
Top View
正面视图



Bottom View
背面视图



Side View
侧面视图



Suggested Solder Pad Layout
Top View

SYMBOL	MILLIMETER		
	MIN	NOM	MAX
D	5.15	5.35	5.55
E	5.95	6.15	6.35
A	0.6	0.73	0.85
A1	0.254 BSC		
A2			0.10
D1	4.01	4.21	4.41
D2	5.00	5.20	5.40
D3	3.54 REF		
D4	2.60 REF		
E1	3.52	3.72	3.92
E2	5.66	5.86	6.06
E4	0.395 REF		
E5	3.74 REF		
E6	1.53 REF		
L1	0.50	0.61	0.71
L2	0.355 BSC		
b	0.30	0.40	0.50
e	1.27 BSC		

Note:

1. Controlling dimension: in millimeters.
2. General tolerance: ± 0.10 mm.
3. The pad layout is for reference purposes only.

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